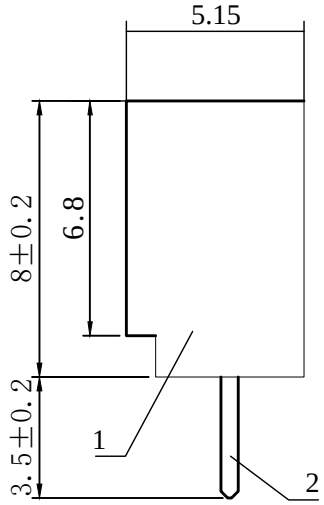
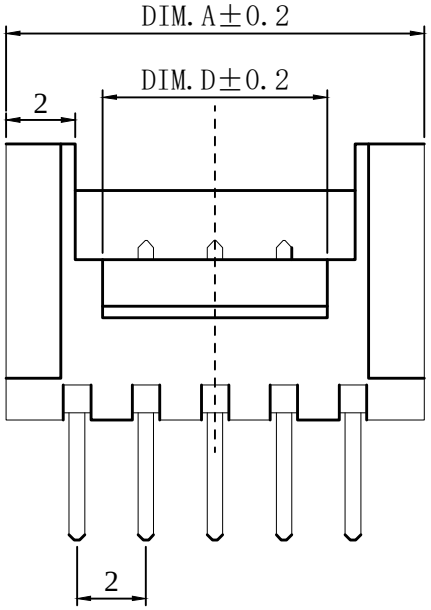
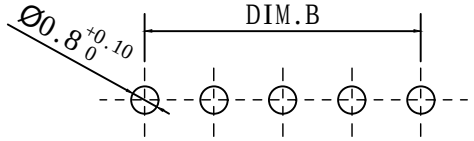
REV.	EC#	DESCRIPTION	DATE DRAWN	CHECK	APPROVED
1.00		初版发行	2020-8-28	胡海萍	胡海萍

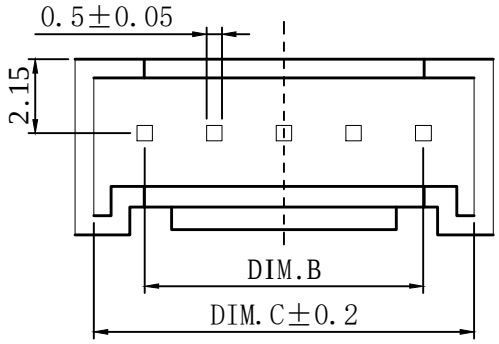




16P	34.0	30.0	32.9	27.5
15P	32.0	28.0	30.9	25.5
14P	30.0	26.0	28.9	23.5
13P	28.0	24.0	26.9	21.5
12P	26.0	22.0	24.9	19.5
11P	24.0	20.0	22.9	17.5
10P	22.0	18.0	20.9	15.5
9P	20.0	16.0	18.9	13.5
8P	18.0	14.0	16.9	11.6
7P	16.0	12.0	14.9	9.5
6P	14.0	10.0	12.9	7.5
5P	12.0	8.0	10.9	6.5
4P	10.0	6.0	8.9	4.5
3P	8.0	4.0	6.9	2.5
2P	6.0	2.0	4.9	2.5
PIN	DIM.A	DIM.B	DIM.C	DIM.D



PCB LAYOUT



温度范围：-25℃~85℃
额定电压：200V AC/DC
额定电流：2A AC/DC
接触电阻：≤0.02Ω
绝缘电阻：≥1000MΩ
耐 压 值：500V AC/minute
适用基板厚度：1.6mm

技术要求:

1) 材质:见附表;
2) 电镀:见附表;
3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
4) 端子表面无氧化、电镀不良等现象。

GENERAL TOLERANCES			
DIM	TOL	DIM	DEG
X.		X°.	±3.00°
X.X	±0.35	X.X°	±2.00°
X.XX	±0.25	X.XX°	±1.00°
X.XXX	±0.15	X.XXX°	

NO.	NAME	Q'TY	DESCRIPTION
2	PIN	n PCS	材质:黄铜,电镀:镀亮锡
1	Housing	1 PCS	材质:PA66 (UL94V-0),颜色:本色

东莞市文章济美电子有限公司

DRAW :	瞿寿坤	2020-8-28
DESIGN:	瞿寿坤	2020-8-28
CHECK:	胡海萍	2020-8-28
APPROVED	胡海萍	2020-8-28

TITLE: WAFER 2.0HYA 立式 DIP

DRAW NAME: 5001-HY0020C-12P1-02-B

SERIES:

P/N:

DRAW NO.

REV. 1.00 SCALE N/A

UNIT: mm SHEET: 1/1